

# 導熱膏 S606 Thermal Compound



## 產品特性 Features

Good thermal conductivity 良好的導熱性  
 Easy to assemble 容易施工  
 High stability 高穩定性  
 Would not harden 不乾硬化

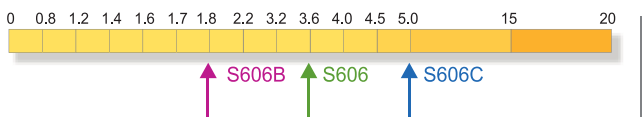
## 產品應用端 Applications

Electronic components: IC、CPU、MOS  
 LED、M/B、P/S、Heat Sink、  
 LCD-TV、Notebook PC、PC、Telecom Device、Wireless Hub.....etc.  
 DDR II Module、DVD Applications、Hand-set applications.....etc.

## 產品物性 Properties

- ◆ REACH Compliant 符合REACH 規範
- ◆ RoHS Compliant 符合RoHS規範

Thermal Conductivity 熱傳導熱率: ( W / m.k、Z axis )



S606B Thermal Conductivity 1.8 W/m.k  
 S606 Thermal Conductivity 3.6 W/m.k  
 S606C Thermal Conductivity 5.0 W/m.k

Property	S606	S606B	S606C	Unit	Test Method
Color 顏色	White白	White白	Gray 灰	-	Visual
Thermal Conductivity 導熱係數	3.6	1.8	5	W/m.k	ASTM D5470
Weight Loss 重量損失	<0.5	<0.5	<0.5	%	ASTM E595
Specific Gravity 比重	2.3	2.3	2.3	g/cm <sup>3</sup>	ASTM D792
Working Temperature 工作溫度	-40 ~ +180	-40 ~ +180	-40 ~ +180	°C	-
Volume Resistance 體積阻抗	>10 <sup>12</sup>	>10 <sup>12</sup>	>10 <sup>12</sup>	Ohm-cm	ASTM D257
Standar Package 標準包裝	1kg	1kg	1kg	kg/pot	-

Need sample 樣品需求? S606(C) - 30 gram  
 1. Choose the P/N  
 2. Fill the quantity you need

## 保存方式 Storage

S606 系列在其未開封之狀態，於室溫25°C以下可保存18個月。

S606 has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened contained at, or below 25°C.

